

4M-BIT CMOS FAST SRAM
1M-WORD BY 4-BIT
Description

The μ PD444004L is a high speed, low power, 4,194,304 bits (1,048,576 words by 4 bits) CMOS static RAM.

Operating supply voltage is $3.3\text{ V} \pm 0.3\text{ V}$.

The μ PD444004L is packaged in a 32-pin plastic SOJ and 32-pin plastic TSOP (II).

Features

- 1,048,576 words by 4 bits organization
- Fast access time : 8, 10, 12 ns (MAX.)
- Output Enable input for easy application
- Single +3.3 V power supply

Ordering Information

Part number	Package	Access time ns (MAX.)	Supply current mA (MAX.)	
			At operating	At standby
μ PD444004LLE-A8	32-pin plastic SOJ (10.16 mm (400))	8	180	5
μ PD444004LLE-A10		10	160	
μ PD444004LLE-A12		12	150	
★ μ PD444004LG5-A8-7JD ^{Note}	32-pin plastic TSOP (II) (10.16 mm (400)) (Normal bent)	8	180	
★ μ PD444004LG5-A10-7JD ^{Note}		10	160	
★ μ PD444004LG5-A12-7JD ^{Note}		12	150	

★ **Note** Under development

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Pin Configurations (Marking Side)

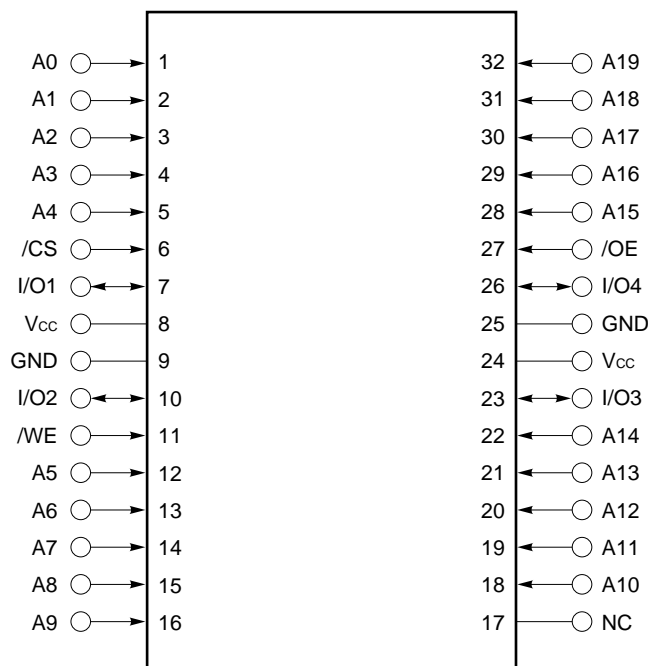
/xxx indicates active low signal.

32-pin plastic SOJ (10.16 mm (400))

[μPD444004LLE]

32-pin plastic TSOP (II) (10.16 mm (400)) (Normal bent)

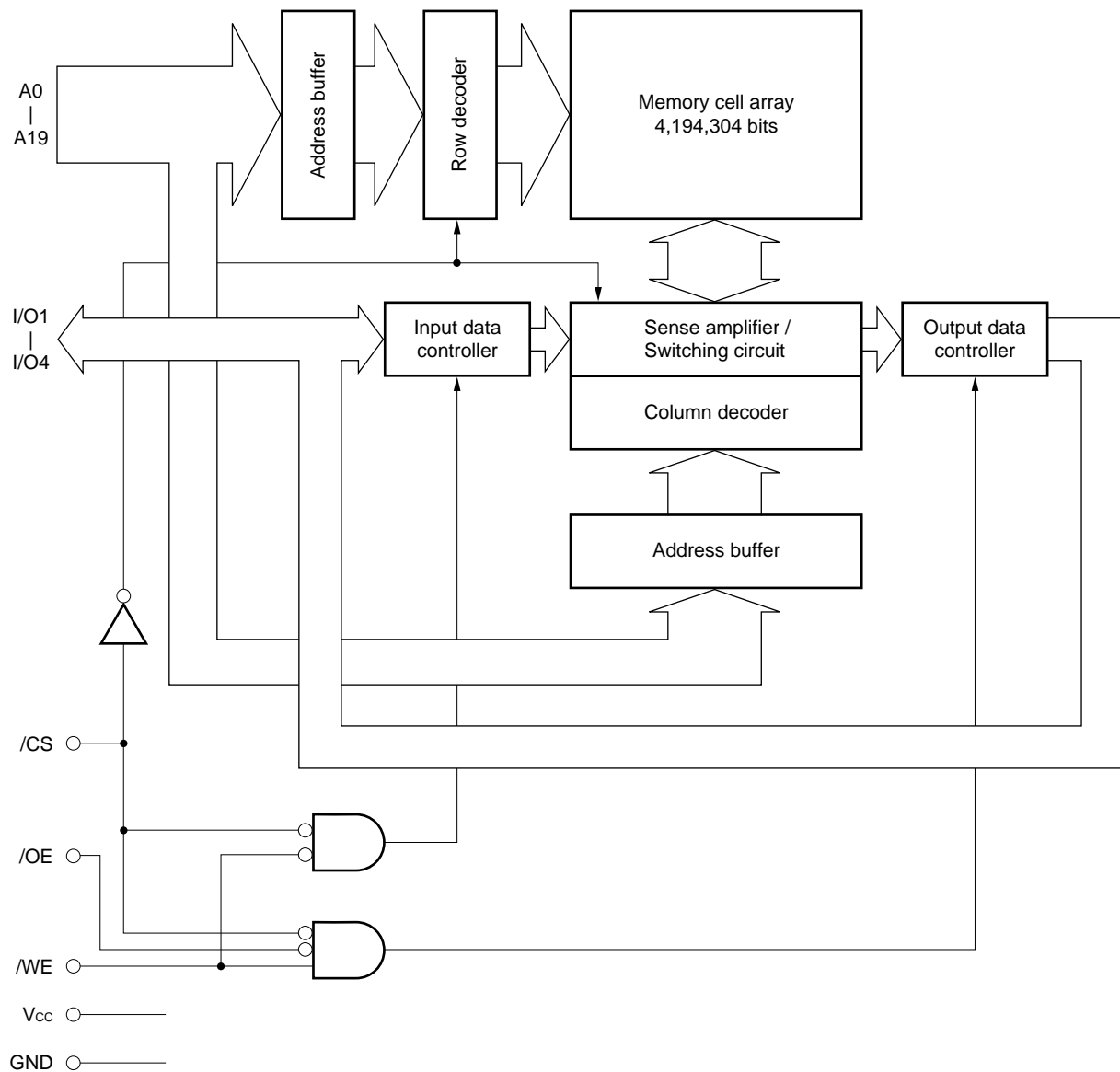
[μPD444004LG5-xxx-7JD]



A0 - A19 : Address Inputs
 I/O1 - I/O4 : Data Inputs / Outputs
 /CS : Chip Select
 /WE : Write Enable
 /OE : Output Enable
 V_{cc} : Power supply
 GND : Ground
 NC : No connection

Remark Refer to **Package Drawings** for the 1-pin index mark.

Block Diagram



Truth Table

/CS	/OE	/WE	Mode	I/O	Supply current
H	×	×	Not selected	High impedance	I _{SB}
L	L	H	Read	D _{OUT}	I _{CC}
L	×	L	Write	D _{IN}	
L	H	H	Output disable	High impedance	

Remark \times : Don't care

Electrical Specifications

Absolute Maximum Ratings

	Parameter	Symbol	Condition	Rating	Unit
★	Supply voltage	V _{CC}		-0.5 ^{Note} to +4.0	V
★	Input / Output voltage	V _I		-0.5 ^{Note} to +4.0	V
	Operating ambient temperature	T _A		0 to 70	°C
	Storage temperature	T _{stg}		-55 to +125	°C

Note -2.0 V (MIN.) (pulse width : 2 ns)

Caution Exposing the device to stress above those listed in Absolute Maximum Rating could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V _{CC}		3.0	3.3	3.6	V
High level input voltage	V _{IH}		2.0		V _{CC} +0.3	V
Low level input voltage	V _{IL}		-0.3 ^{Note}		+0.8	V
Operating ambient temperature	T _A		0		70	°C

Note -2.0 V (MIN.) (pulse width : 2 ns)

DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input leakage current	I_{LI}	$V_{IN} = 0\text{ V to }V_{CC}$	-2		+2	μA
Output leakage current	I_{LO}	$V_{I/O} = 0\text{ V to }V_{CC}$, $/CS = V_{IH}$ or $/OE = V_{IH}$ or $/WE = V_{IL}$	-2		+2	μA
Operating supply current	I_{CC}	$/CS = V_{IL}$, Cycle time : 8 ns			180	mA
		$I_{I/O} = 0\text{ mA}$, Cycle time : 10 ns			160	
		Minimum cycle time Cycle time : 12 ns			150	
Standby supply current	I_{SB}	$/CS = V_{IH}$, $V_{IN} = V_{IH}$ or V_{IL}			40	mA
	I_{SB1}	$/CS \geq V_{CC} - 0.2\text{ V}$, $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$			5	
High level output voltage	V_{OH}	$I_{OH} = -4.0\text{ mA}$	2.4			V
Low level output voltage	V_{OL}	$I_{OL} = +8.0\text{ mA}$			0.4	V

Remarks 1. V_{IN} : Input voltage

$V_{I/O}$: Input / Output voltage

2. These DC characteristics are in common regardless of package types.

Capacitance ($T_A = 25\text{ °C}$, $f = 1\text{ MHz}$)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{IN}	$V_{IN} = 0\text{ V}$			6	pF
Input / Output capacitance	$C_{I/O}$	$V_{I/O} = 0\text{ V}$			8	pF

Remarks 1. V_{IN} : Input voltage

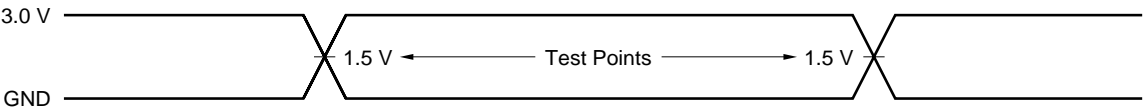
$V_{I/O}$: Input / Output voltage

2. These parameters are periodically sampled and not 100% tested.

AC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

AC Test Conditions

Input Waveform (Rise and Fall Time ≤ 3 ns)



Output Waveform



Output Load

AC characteristics directed with the note should be measured with the output load shown in **Figure 1** or **Figure 2**.

Figure 1

(t_{AA} , t_{ACS} , t_{OE} , t_{OH})

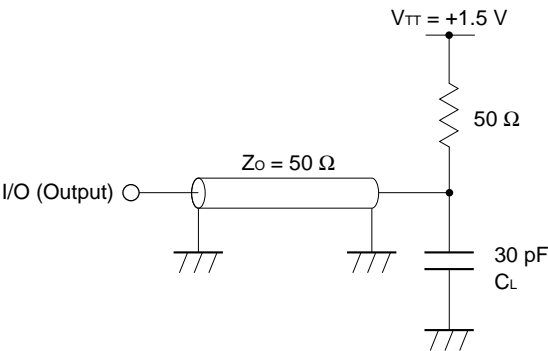
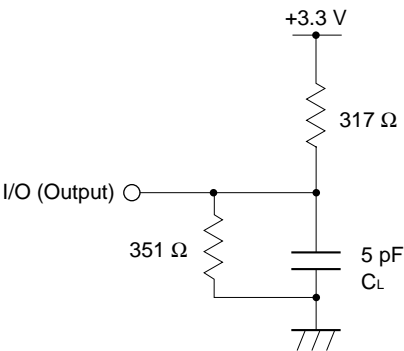


Figure 2

(t_{CLZ} , t_{OLZ} , t_{CHZ} , t_{OHZ} , t_{WHZ} , t_{OW})



Remark C_L includes capacitances of the probe and jig, and stray capacitances.

Read Cycle

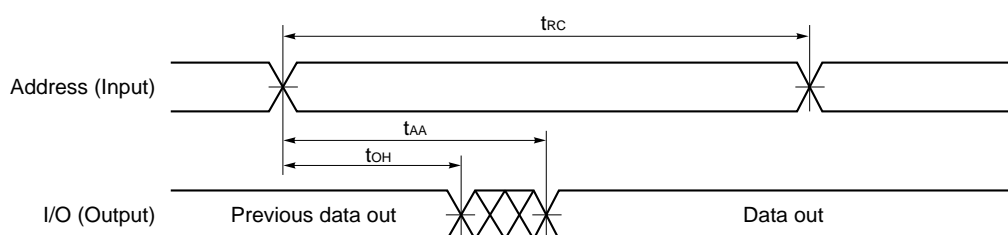
Parameter	Symbol	μPD444004L-A8		μPD444004L-A10		μPD444004L-A12		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t _{RC}	8		10		12		ns	
Address access time	t _{AA}		8		10		12	ns	1
/CS access time	t _{ACS}		8		10		12	ns	
/OE access time	t _{OE}		4		5		6	ns	
Output hold from address change	t _{OH}	3		3		3		ns	
/CS to output in low impedance	t _{CLZ}	3		3		3		ns	2, 3
/OE to output in low impedance	t _{OLZ}	0		0		0		ns	
/CS to output in high impedance	t _{CHZ}		4		5		6	ns	
/OE to output hold in high impedance	t _{OHZ}		4		5		6	ns	

Notes 1. See the output load shown in **Figure 1**.

2. Transition is measured at ± 200 mV from steady-state voltage with the output load shown in **Figure 2**.
3. These parameters are periodically sampled and not 100% tested.

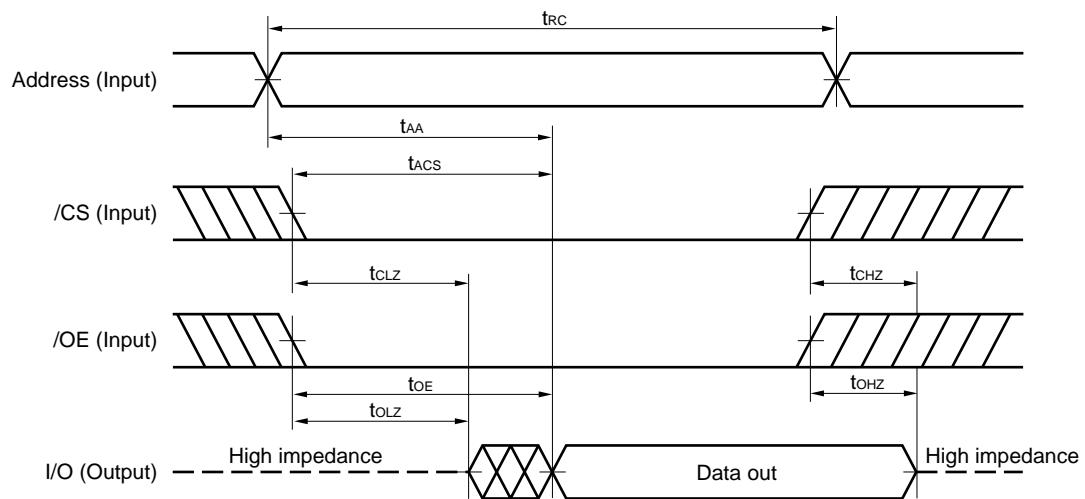
Remark These AC characteristics are in common regardless of package types.

Read Cycle Timing Chart 1 (Address Access)



- Remarks**
1. In read cycle, /WE should be fixed to high level.
 2. /CS = /OE = V_{IL}

Read Cycle Timing Chart 2 (/CS Access)



Caution Address valid prior to or coincident with /CS low level input.

Remark In read cycle, /WE should be fixed to high level.

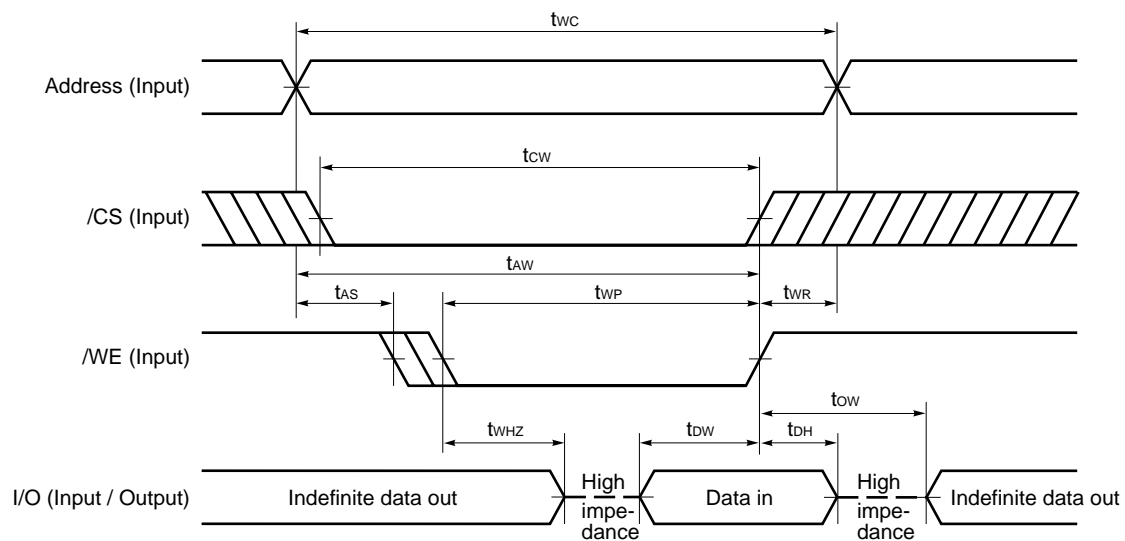
Write Cycle

Parameter	Symbol	μ PD444004L-A8		μ PD444004L-A10		μ PD444004L-A12		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{WC}	8		10		12		ns	
/CS to end of write	t _{CW}	6		7		8		ns	
Address valid to end of write	t _{AW}	6		7		8		ns	
Write pulse width	t _{WP}	6		7		8		ns	
Data valid to end of write	t _{DW}	4		5		6		ns	
Data hold time	t _{DH}	0		0		0		ns	
Address setup time	t _{AS}	0		0		0		ns	
Write recovery time	t _{WR}	0		0		0		ns	
/WE to output in high impedance	t _{WHZ}		4		5		6	ns	1, 2
Output active from end of write	t _{OW}	3		3		3		ns	

Notes 1. Transition is measured at ± 200 mV from steady-state voltage with the output load shown in **Figure 2**.

2. These parameters are periodically sampled and not 100% tested.

Remark These AC characteristics are in common regardless of package types.

Write Cycle Timing Chart 1 (/WE Controlled)

Cautions 1. /CS or /WE should be fixed to high level during address transition.

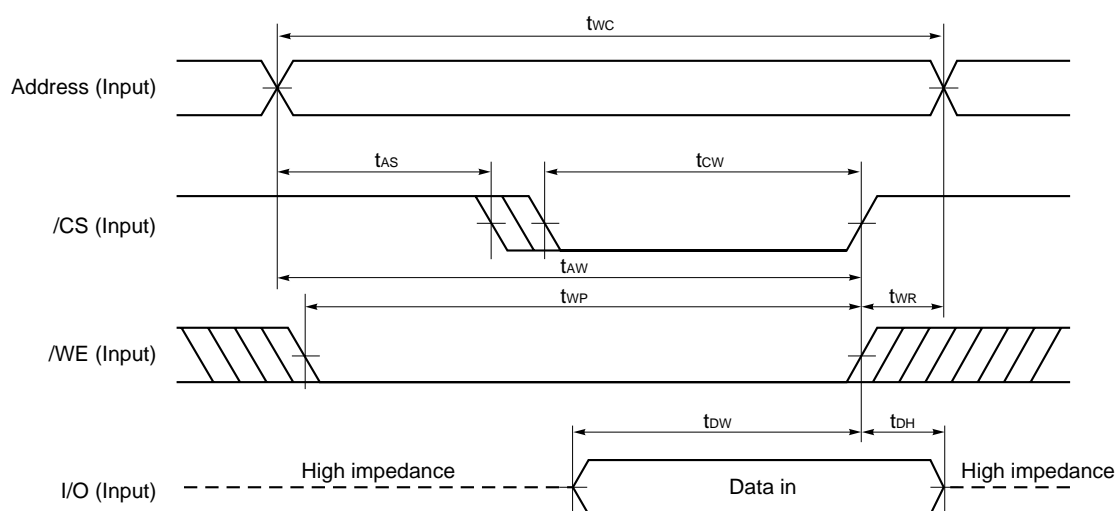
★

2. Do not input data to the I/O pins while they are in the output state.

Remarks 1. Write operation is done during the overlap time of a low level /CS and a low level /WE.

2. When /WE is at low level, the I/O pins are always high impedance. When /WE is at high level, read operation is executed. Therefore /OE should be at high level to make the I/O pins high impedance.

Write Cycle Timing Chart 2 (/CS Controlled)



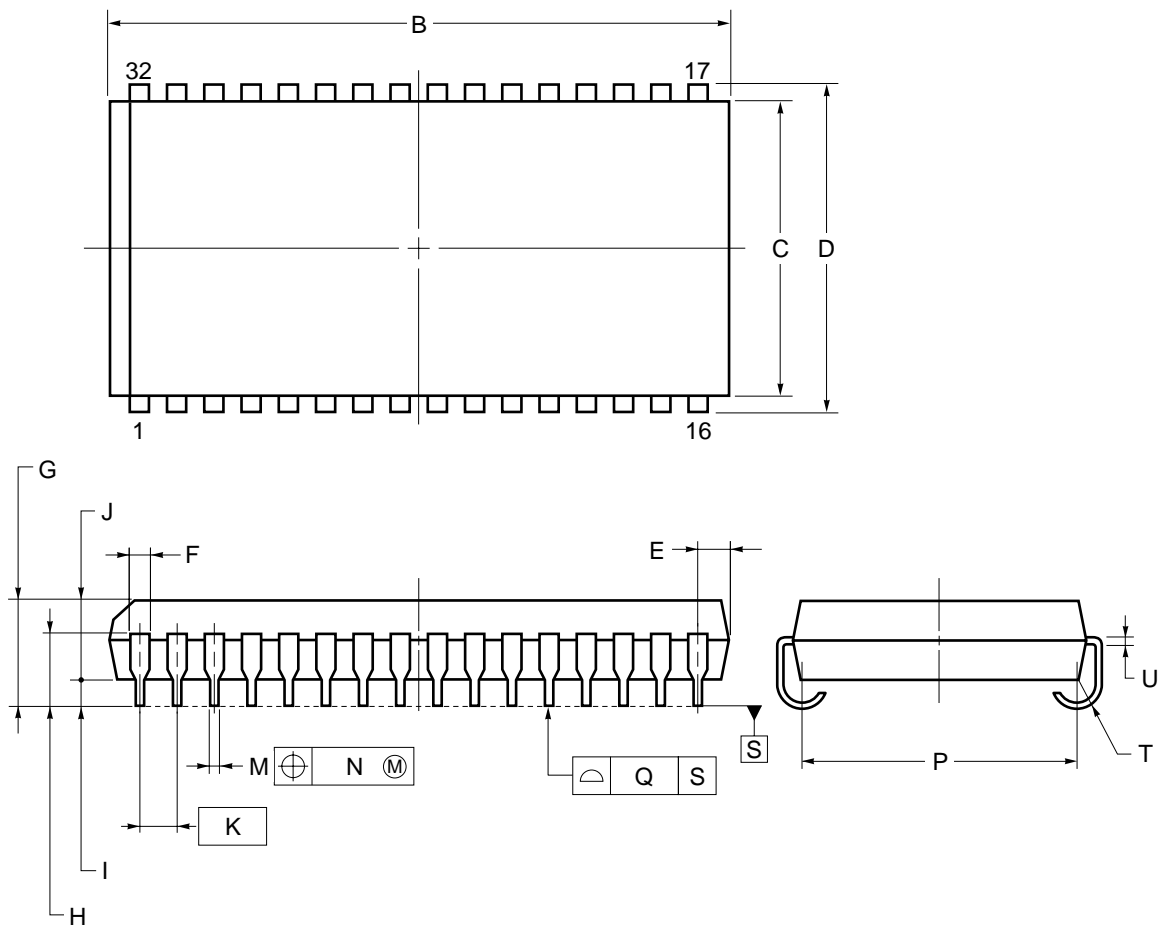
Cautions 1. /CS or /WE should be fixed to high level during address transition.

★ 2. Do not input data to the I/O pins while they are in the output state.

Remark Write operation is done during the overlap time of a low level /CS and a low level /WE.

Package Drawings

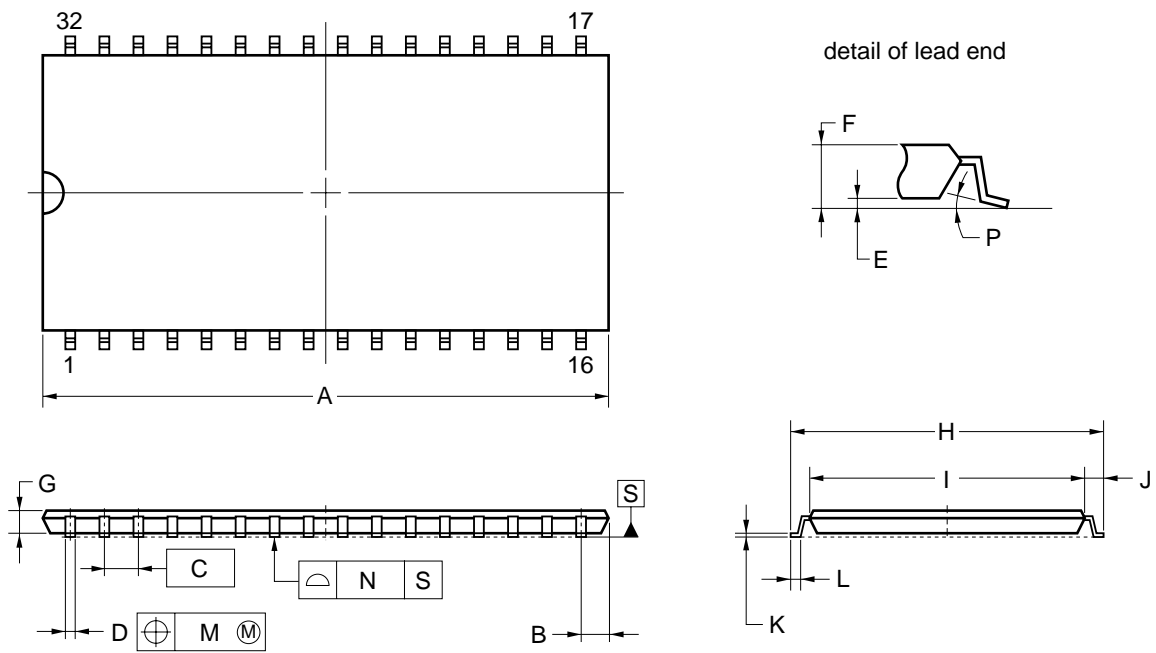
32-PIN PLASTIC SOJ (10.16 mm (400))



NOTE
Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
B	21.26±0.2
C	10.16
D	11.18±0.2
E	1.005±0.1
F	0.74
G	3.5±0.2
H	2.545±0.2
I	0.8 MIN.
J	2.6
K	1.27(T.P.)
M	0.40±0.10
N	0.12
P	9.4±0.20
Q	0.1
T	R0.85
U	0.20 ^{+0.10} _{-0.05}
P32LE-400A-1	

32-PIN PLASTIC TSOP (II) (10.16mm (400))



NOTE
Each lead centerline is located within 0.21 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	21.17 MAX.
B	1.075 MAX.
C	1.27 (T.P.)
D	0.42 ^{+0.08} _{-0.07}
E	0.1±0.05
F	1.2 MAX.
G	0.97
H	11.76±0.2
I	10.16±0.1
J	0.8±0.2
K	0.145 ^{+0.025} _{-0.015}
L	0.5±0.1
M	0.21
N	0.10
P	3° ^{+7°} _{-3°}

S32G5-50-7JD2-1

Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μ PD444004L.

Types of Surface Mount Device

μ PD444004LLE : 32-pin plastic SOJ (10.16 mm (400))

μ PD444004LG5-7JD : 32-pin plastic TSOP (II) (10.16 mm (400)) (Normal bent)

[MEMO]

NOTES FOR CMOS DEVICES**① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS**

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

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